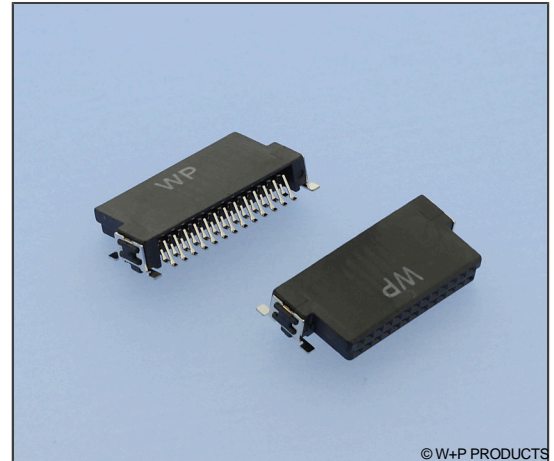


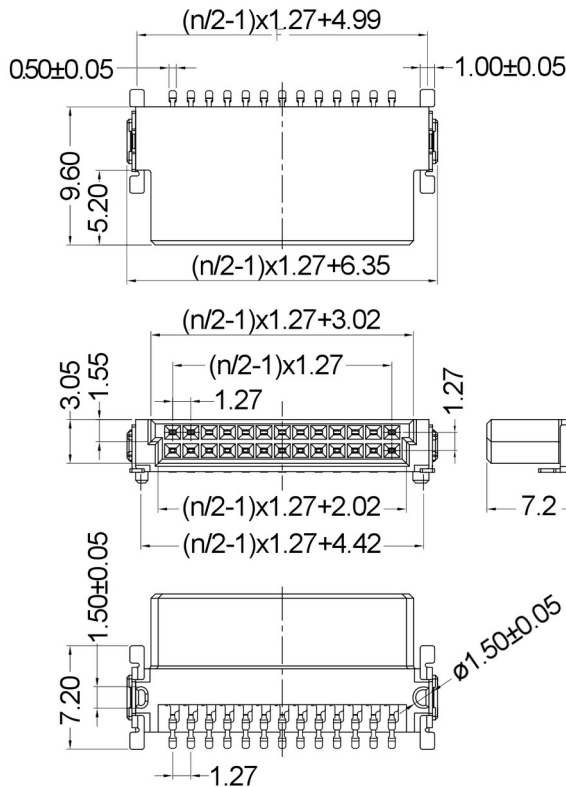
### Technische Daten / Technical Data

Isolierkörper <i>Insulator</i>	Thermoplast, nach UL94 V-0 <i>Thermoplastic, rated UL94 V-0</i>
Kontaktmaterial <i>Contact Material</i>	Kupferlegierung <i>Copper alloy</i>
Kontaktoberfläche <i>Contact Surface</i>	Lt. Oberflächenoptionen, über Ni <i>Acc. to plating options, over Ni</i>
Durchgangswiderstand <i>Contact Resistance</i>	< 25 mΩ
Isolationswiderstand <i>Insulation Resistance</i>	> 1000 MΩ
Spannungsfestigkeit <i>Test Voltage</i>	600 V AC
Nennspannung <i>Voltage Rating</i>	100 V AC
Nennstrom <i>Current Rating</i>	1,7 A max. <i>1.7 A max.</i>
Temperaturbereich <i>Temperature Range</i>	-55 °C ... +125 °C
Verarbeitung <i>Processing</i>	Reflow-Lötverfahren <i>Reflow soldering</i>

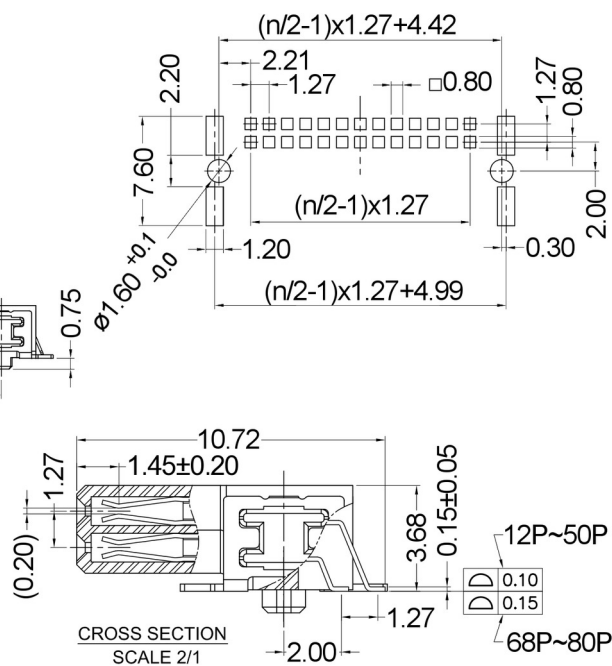


© W+P PRODUCTS

Gegenstecker / Mating Connectors:  
9019 9020



Recommended P.C.B Layout (Top Side)  
(PCB BOARD TOLERANCE  $\pm 0.05$ )



<b>Series</b>	<b>Contacts*</b>	<b>Plating*</b>	<b>Packaging*</b>
<b>9017</b>	<b>50</b>	<b>80</b>	<b>TR</b>
	10/12/16/20/26/30 32/40/50/68/80	60 Sel. Au flash / Sn over Ni 80 Sel. Au 30µ" / Sn over Ni	ST TR

\* Dies ist ein Bestellbeispiel - bitte durch Ihre Spezifikationen ersetzen.  
\* This is an order example - please replace by your specifications.

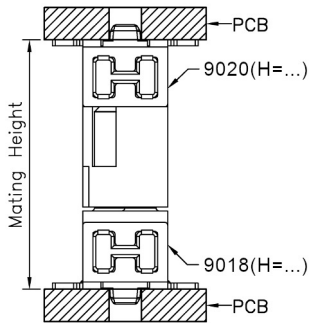
### Lieferformen / Packaging Options:

- ST In Stangen ohne Pick&Place-Pads / In tubes w/o Pick & Place Pads
- TR Tape & Reel ohne Pick&Place-Pads / Tape & reel w/o Pick & Place Pads

# 9017 9018 9019 9020

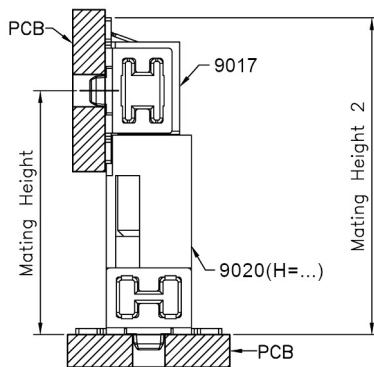
## Übersicht über die erreichbaren Bauhöhen Chart of Attainable Mating Heights

9018 + 9020



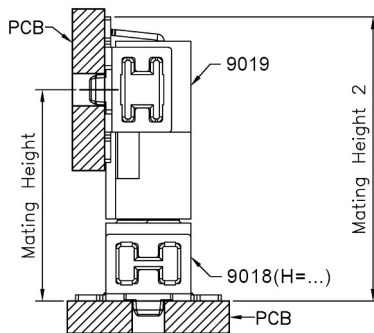
Mating Height		9020		
		H=6.75mm	H=8.25mm	H=9.85mm
9018	H=6.25mm	8.0 - 9.5	9.5 - 11.0	11. - 12.6
	H=9.05mm	10.8 - 12.3	12.3 - 13.8	13.9 - 15.4
	H=13.65mm	15.4 - 16.9	16.9 - 18.4	18.5 - 20.0

9017 + 9020



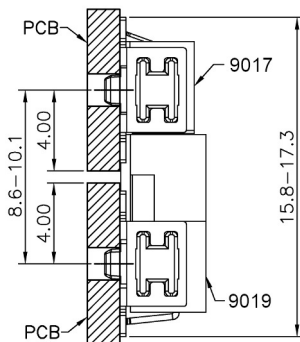
Mating Heights		9020		
		H=6.75mm	H=8.25mm	H=9.85mm
9017	8.95 - 10.45	10.45 - 11.95	12.05 - 13.55	
	12.55 - 14.05	14.05 - 15.55	15.65 - 17.15	

9018 + 9019



Mating Heights		9018		
		H=6.25mm	H=9.05mm	H=13.65mm
9019	7.65 - 9.15	10.45 - 11.95	15.05 - 16.55	
	11.25 - 12.75	14.05 - 15.55	18.65 - 20.15	

9017 + 9019



Für 9017 und 9019 bestehen keine Bauhöhenoptionen. Der gekennzeichnete Abstand beträgt 15.80 - 17.30mm.

There are no profile options for 9017 and 9019. The marked dimension is 15.80 - 17.30mm.

### Reflow-Lötempfehlung für kurze Lötzeiten

Die Bauteile sollten gemäß folgendem Temperatur-Profil in Anlehnung an die IPC/JEDEC J-STD-020C für bleifreies Löten im Reflow-Verfahren verarbeitet werden (Maximalwerte).

Profileigenschaft	Kennwert
Temperatur Minimum $T_{Smin}$	150 °C
Temperatur Maximum $T_{Smax}$	200 °C
Dauer $T_{Smin} - T_{Smax}$	60 – 180s
Temperatur Lötbereich $T_L$	217 °C
Verweildauer oberhalb $T_L$	60 – 180s
Ramp-Up Rate $T_{Smax} - T_P$	max. 3 °C / s
Höchsttemperatur $T_P$	260±5 °C
Dauer Höchsttemperatur	20 – 40s
Ramp-Down Rate $T_{Pmax} - T_{Smin}$	6 °C / s
Dauer 25 °C – Höchsttemperatur $T_P$	max. 8m

### Reflow Soldering Recommendation For Shorter Peak Times

Items should be soldered according to IPC/JEDEC J-STD-020C temperature profile for leadfree reflow soldering (maximum values).

Profile Feature	Key Values
Minimum Temperature $T_{Smin}$	150 °C
Maximum Temperatur $T_{Smax}$	200 °C
Duration $T_{Smin} - T_{Smax}$	60 – 180s
Soldering Range Temperature $T_L$	217 °C
Duration above $T_L$	60 – 180s
Ramp-Up Rate $T_{Smax} - T_P$	max. 3 °C / s
Peak Temperature $T_P$	260±5 °C
Duration Peak Temperature	20 – 40s
Ramp-Down Rate $T_{Pmax} - T_{Smin}$	6 °C / s
Duration 25°C - Peak Temp. $T_P$	max. 8min

